



Description

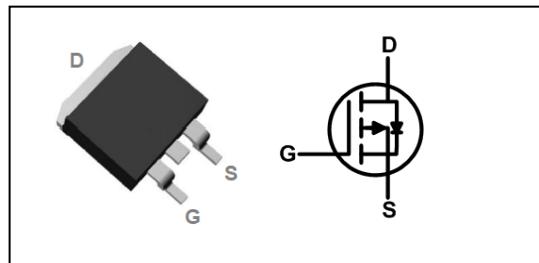
The HSH047P06 is the high cell density trenched P-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The HSH047P06 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

Product Summary

V _{DS}	-60	V
R _{DSON,typ}	3.9	mΩ
I _D	-150	A

TO263 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	-60	V
V _{GS}	Gate-Source Voltage	±20	V
I _D @T _C =25°C	Continuous Drain Current ¹	-150	A
I _D @T _C =100°C	Continuous Drain Current ¹	-85	A
I _{DM}	Pulsed Drain Current ²	-520	A
EAS	Single Pulse Avalanche Energy ³	480	mJ
P _D @T _C =25°C	Total Power Dissipation ⁴	183	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-Ambient ¹	---	62	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	---	0.68	°C/W

P-Ch 60V Fast Switching MOSFETs
Electrical Characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_D=-250\mu\text{A}$	-60	---	---	V
$\text{R}_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance ²	$\text{V}_{\text{GS}}=-10\text{V}$, $\text{I}_D=-50\text{A}$	---	3.9	4.7	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=-4.5\text{V}$, $\text{I}_D=-30\text{A}$	---	4.8	6.2	
$\text{V}_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}$, $\text{I}_D=-250\mu\text{A}$	-1.0	-1.5	-2.5	V
I_{bss}	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=-48\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $\text{T}_J=25^{\circ}\text{C}$	---	---	-1	uA
		$\text{V}_{\text{DS}}=-48\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $\text{T}_J=55^{\circ}\text{C}$	---	---	-10	
I_{GSS}	Gate-Source Leakage Current	$\text{V}_{\text{GS}}=\pm 20\text{V}$, $\text{V}_{\text{DS}}=0\text{V}$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$\text{V}_{\text{DS}}=-10\text{V}$, $\text{I}_D=-3\text{A}$	---	18	---	S
Q_{g}	Total Gate Charge (-4.5V)	$\text{V}_{\text{DS}}=-48\text{V}$, $\text{V}_{\text{GS}}=-10\text{V}$, $\text{I}_D=-5\text{A}$	---	280	---	nC
Q_{gs}	Gate-Source Charge		---	55	---	
Q_{gd}	Gate-Drain Charge		---	24	---	
$\text{T}_{\text{d}(\text{on})}$	Turn-On Delay Time	$\text{V}_{\text{DD}}=-48\text{V}$, $\text{V}_{\text{GS}}=-10\text{V}$, $\text{R}_G=6\Omega$, $\text{I}_D=1\text{A}$	---	88	---	ns
T_r	Rise Time		---	258	---	
$\text{T}_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	509	---	
T_f	Fall Time		---	244	---	
C_{iss}	Input Capacitance	$\text{V}_{\text{DS}}=-25\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	17900	---	pF
C_{oss}	Output Capacitance		---	1701	---	
C_{rss}	Reverse Transfer Capacitance		---	680	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current ^{1,5}	$\text{V}_G=\text{V}_D=0\text{V}$, Force Current	---	---	-150	A
V_{SD}	Diode Forward Voltage ²	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_s=-40\text{A}$, $\text{T}_J=25^{\circ}\text{C}$	---	---	-1	V
Tr	Reverse Recovery Time	$\text{I}_{\text{sd}}=-10\text{A}, \text{dI}/\text{dt}=100\text{A}/\text{us}$	---	46	---	ns
Qrr	Reverse Recovery Charge		---	117	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $\text{V}_{\text{DD}}=-25\text{V}, \text{V}_{\text{GS}}=-10\text{V}, \text{L}=0.1\text{Mh}, \text{I}_{\text{as}}=98\text{A}$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.



Typical Characteristics

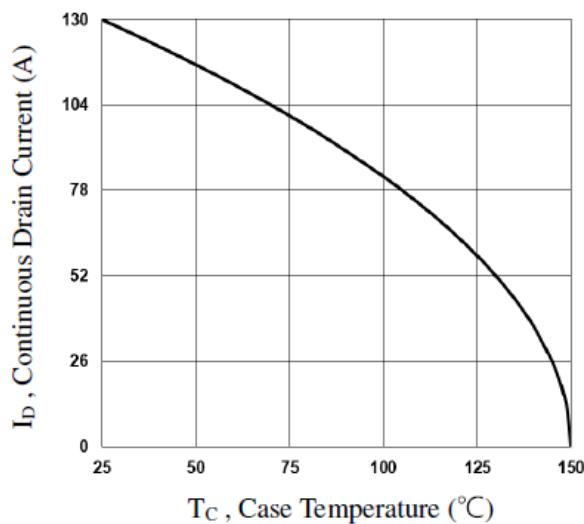


Fig.1 Continuous Drain Current vs. T_c

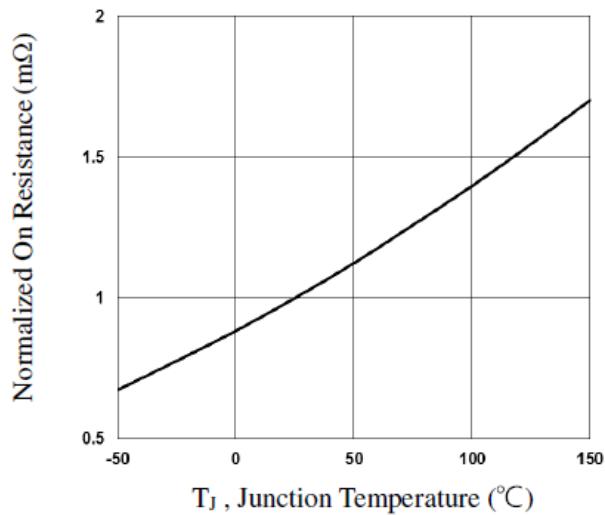


Fig.2 Normalized RDSON vs. T_j

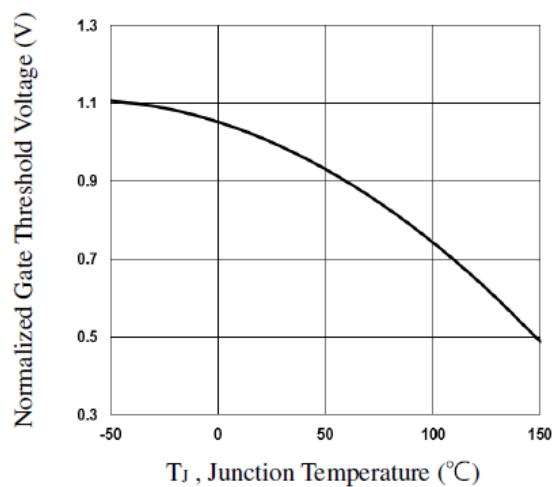


Fig.3 Normalized V_{th} vs. T_j

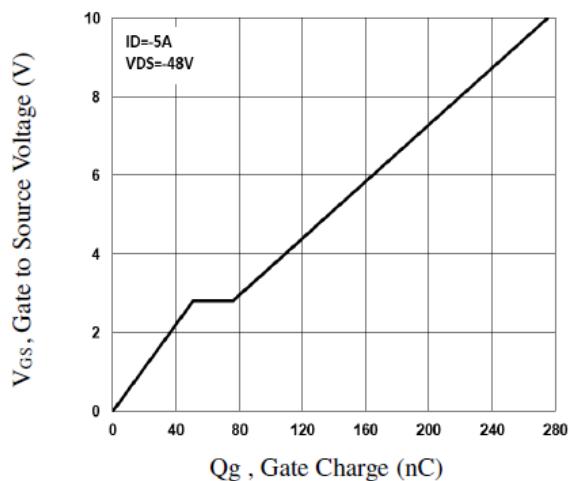


Fig.4 Gate Charge Characteristics

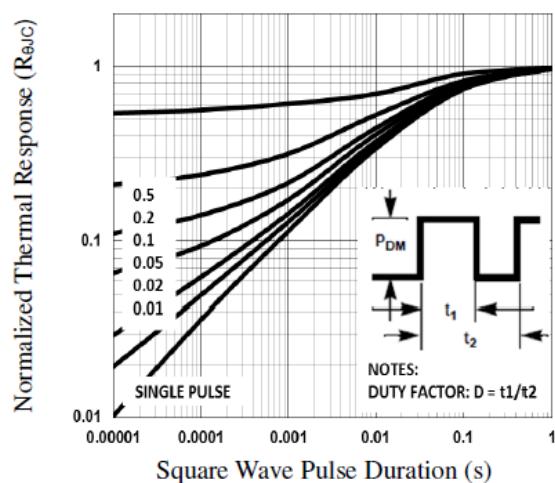


Fig.5 Normalized Transient Impedance

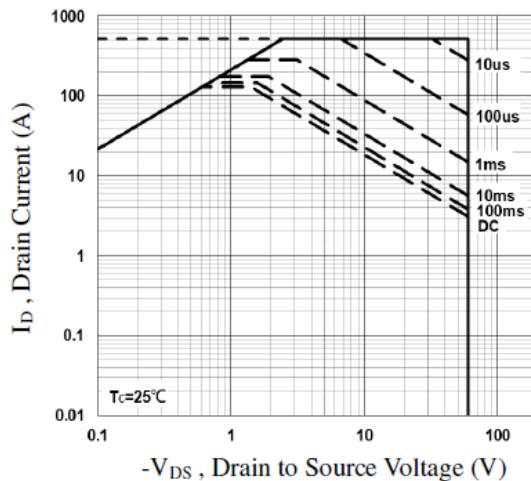


Fig.6 Maximum Safe Operation Area



P-Ch 60V Fast Switching MOSFETs

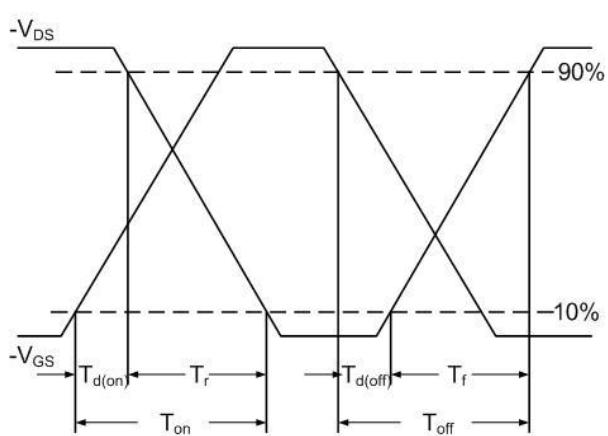


Fig.7 Switching Time Waveform

$$EAS = \frac{1}{2} L \times (-I_{AS})^2 \times \frac{-BV_{DSS}}{-BV_{DSS} - (-V_{DD})}$$

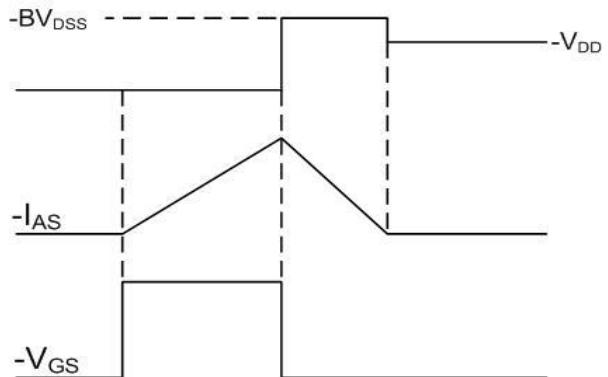
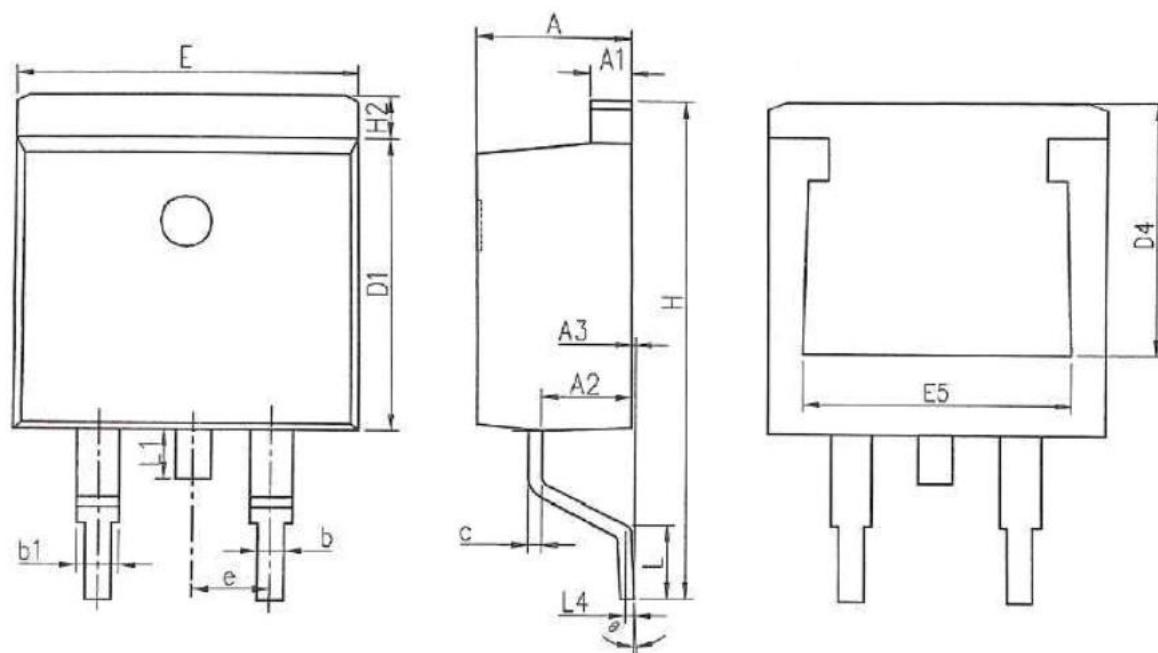


Fig.8 Gate Charge Waveform



P-Ch 60V Fast Switching MOSFETs



SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.370	4.770	0.172	0.188
A1	1.220	1.420	0.048	0.056
A2	2.200	2.890	0.087	0.114
A3	0.000	0.250	0.000	0.010
b	0.700	0.960	0.028	0.038
b1	1.170	1.470	0.046	0.058
c	0.300	0.530	0.012	0.021
D1	8.500	9.300	0.335	0.366
D4	6.600	-	0.260	-
E	9.860	10.36	0.388	0.408
E5	7.060	-	0.278	-
e	2.540 BSC		0.100 BSC	
H	14.70	15.70	0.579	0.618
H2	1.070	1.470	0.042	0.058
L	2.000	2.600	0.079	0.102
L1	1.400	1.750	0.055	0.069
L4	0.250 BSC		0.010 BSC	
θ	0°	9°	0°	9°